



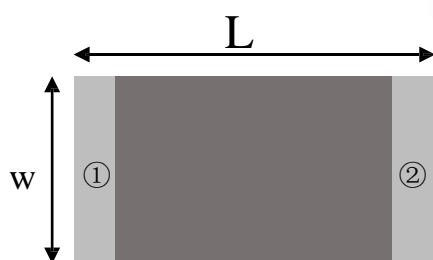
Features

1. Surface mounted devices with a small dimension of $1.6 \times 0.8 \times 0.8$ mm meet future miniaturization trend.
2. Embedded and LTCC (low temperature co-fired ceramic) technology is able to integrate with system design as well as beautifying the housing of final product.
3. High stability and low tolerance.

Applications

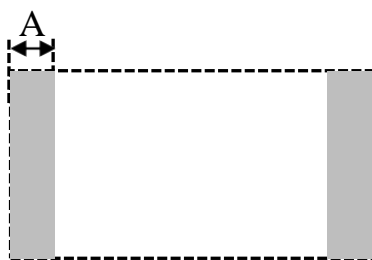
1. Bluetooth
2. Wireless LAN
3. ISM band 2.4GHz wireless applications

Dimensions (Unit: mm)

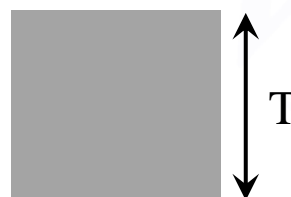


(Top View)

Number	Terminal Name
①	INPUT
②	NC



(Bottom View)

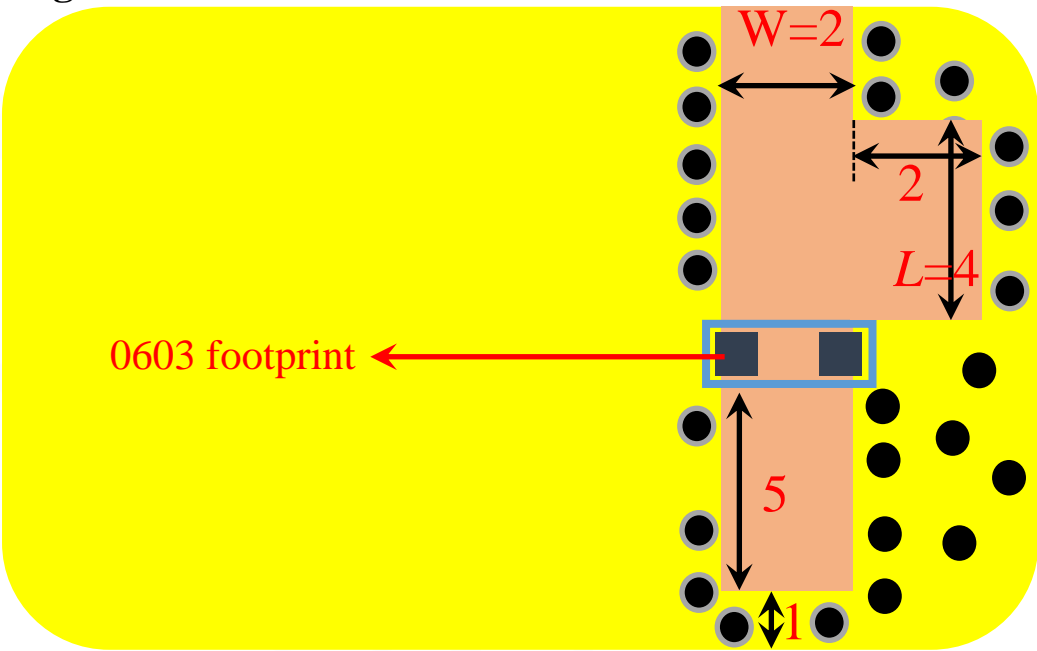


(Side View)

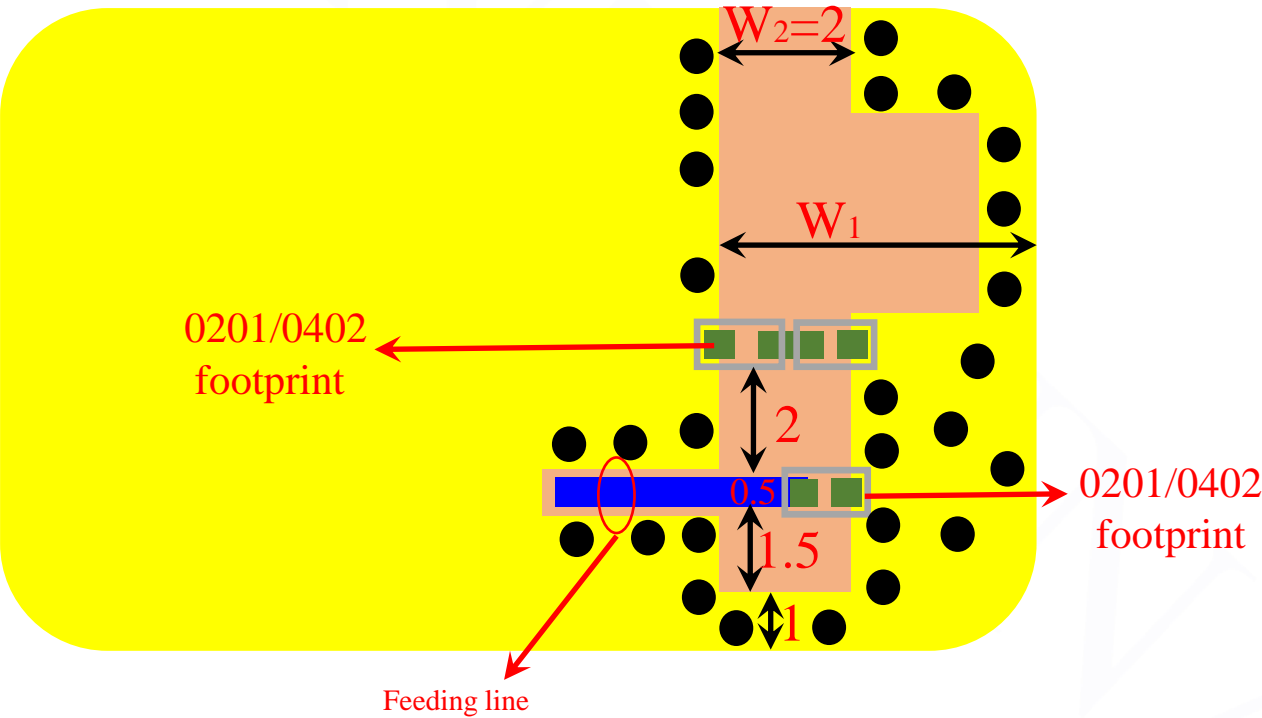
Symbols	L	W	T	A
Dimensions	1.60 ± 0.20	0.80 ± 0.20	0.80 ± 0.20	0.30 ± 0.10



Matching Circuits

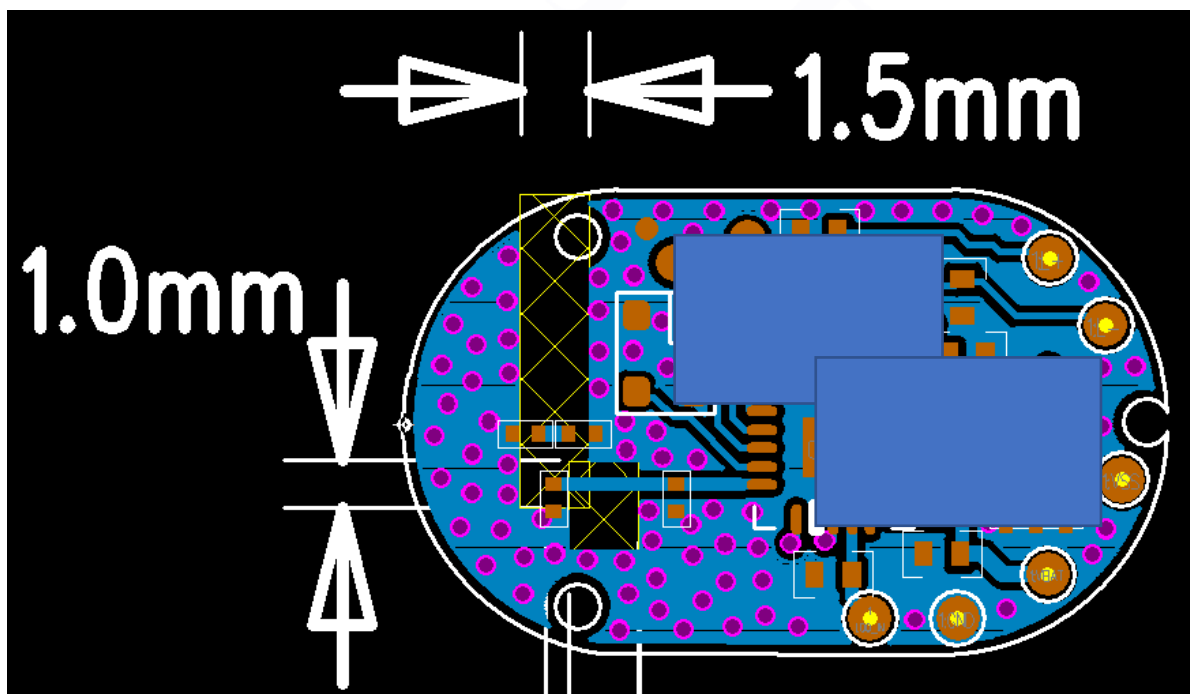
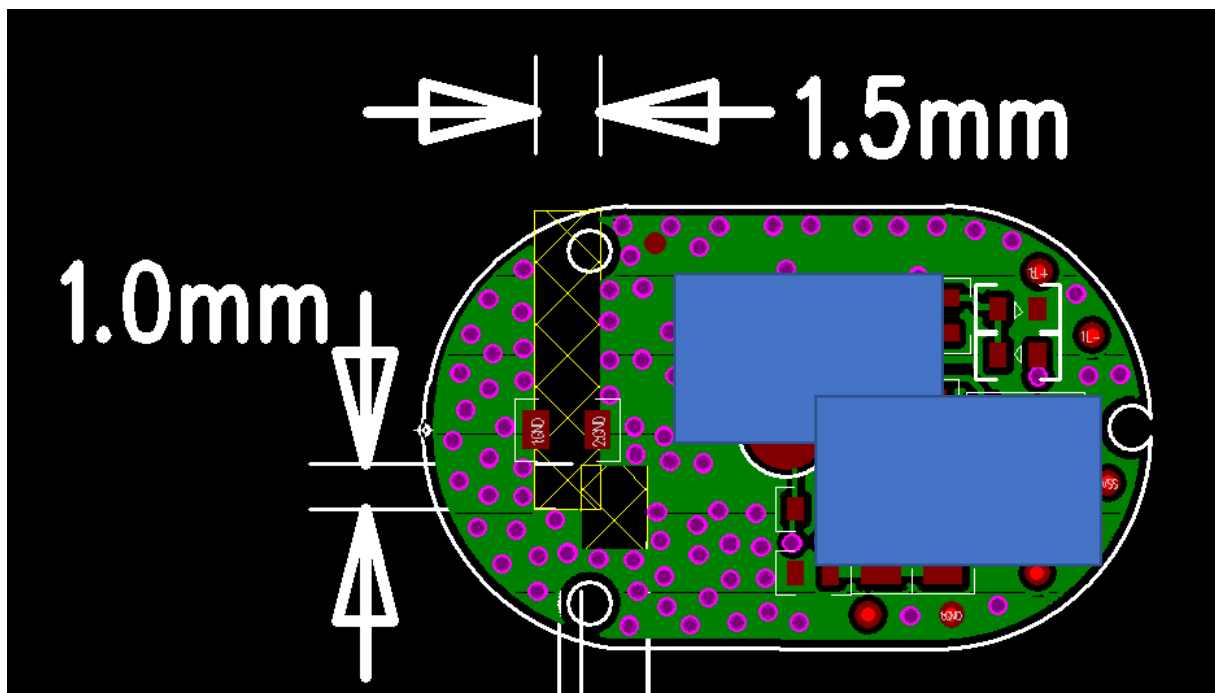


Unit:mm





Application example-2



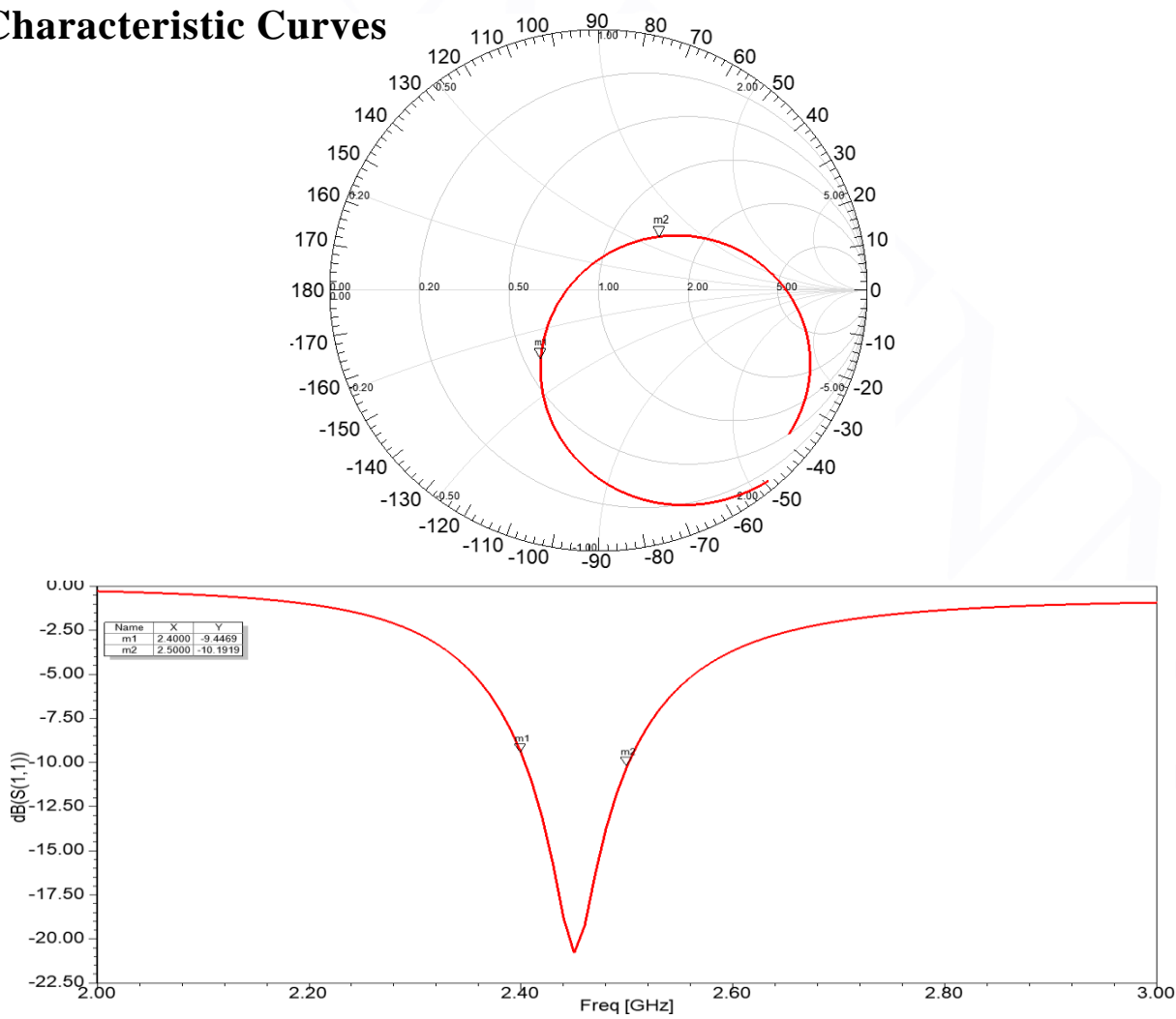


P/N: HY160808 SRF07

Electrical Characteristics

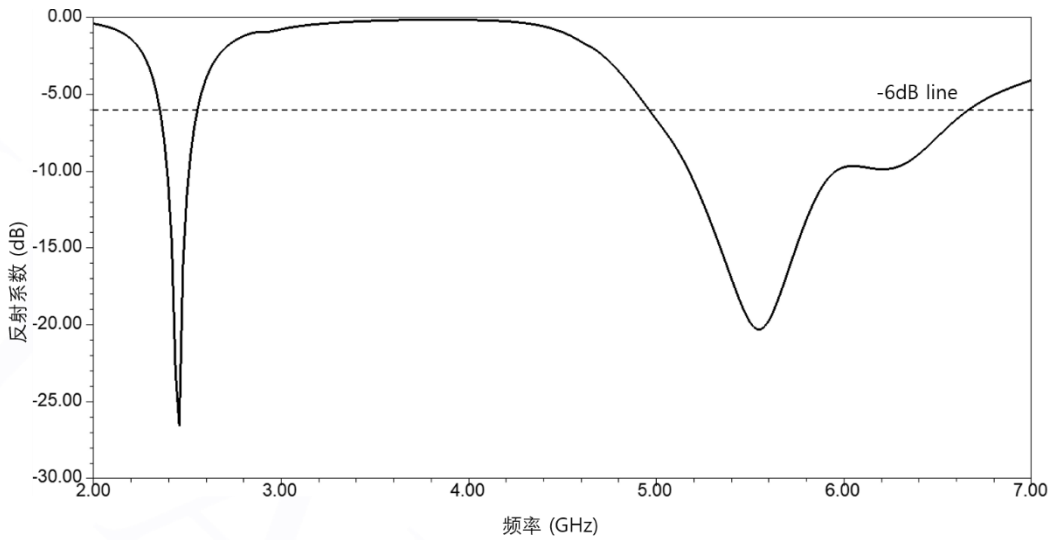
	Feature	Specification
1	Central frequency	2.45GHz
2	Bandwidth	100MHz
3	Peak gain	3dBi
4	VSWR	<2
5	Polarization	Linear
6	Azimuth beamwidth	Omnidirectional
7	Impedance	50 Ω

Characteristic Curves

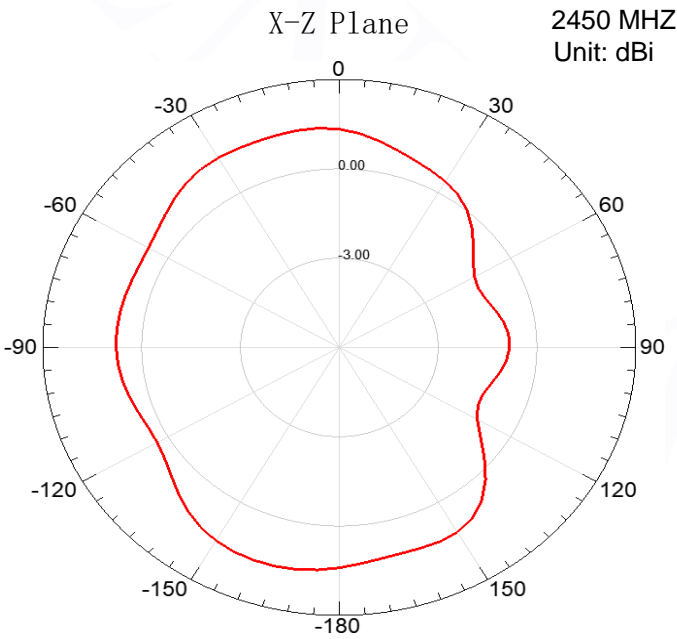
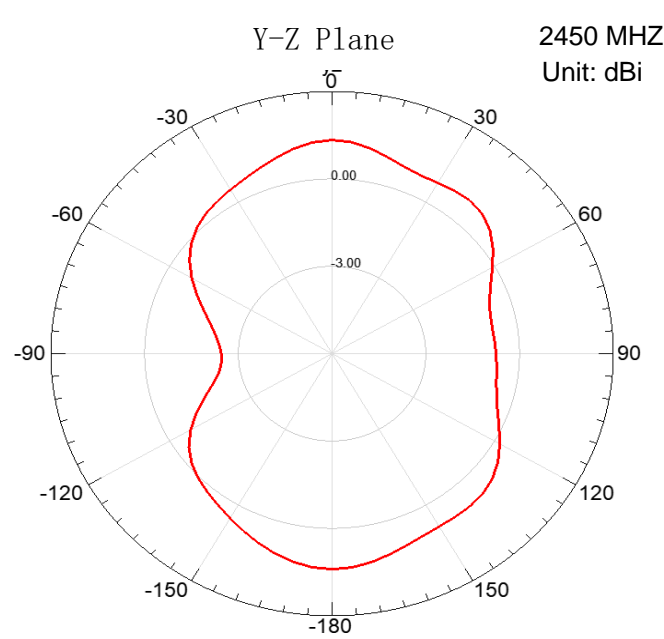
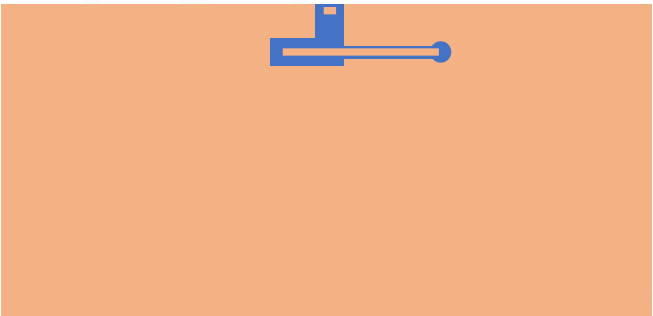
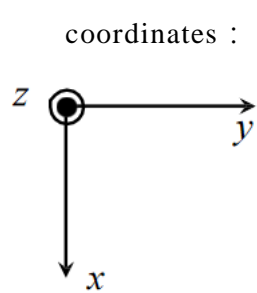




P/N: HY160808 SRF07

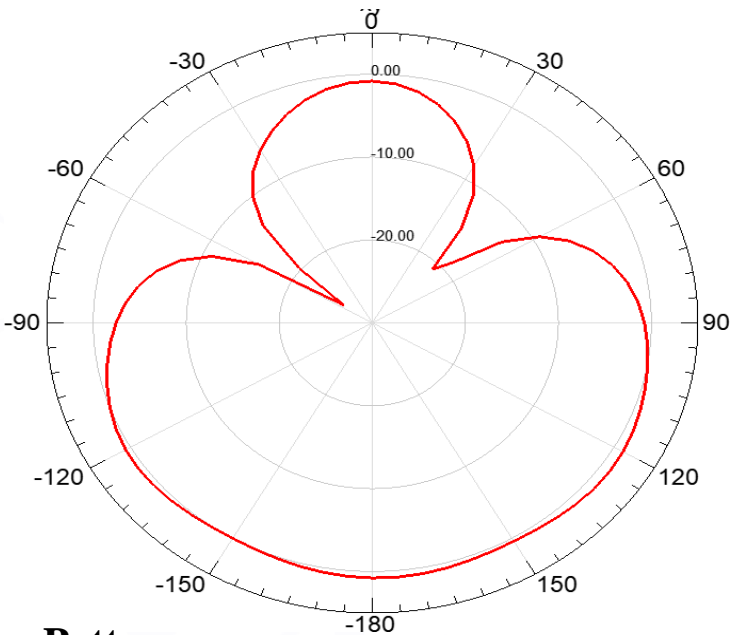


Radiation Pattern



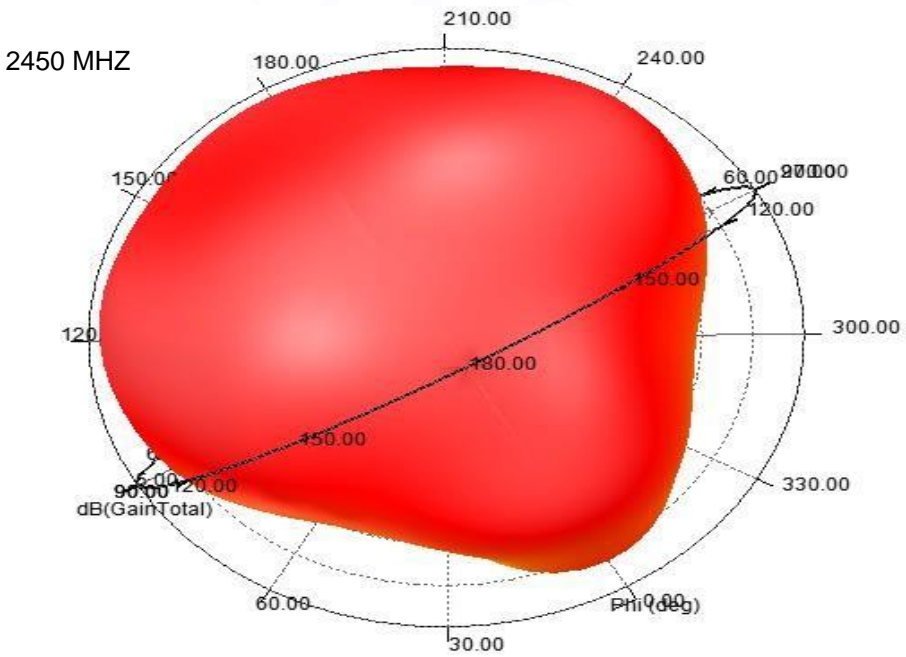


P/N: HY160808 SRF07



2450 MHZ
Unit: dBi

3D Radiation Pattern



Frequency	2450MHz
Avg. gain	-0.85dBi
Peak gain	3.0dBi
Efficiency	82%



Dependability Test

Test Temperature	25℃±3℃
Operating Temperature	-25℃~+85℃
Temperature	5~40℃
Relative Humidity	20~70%

Moisture Proof

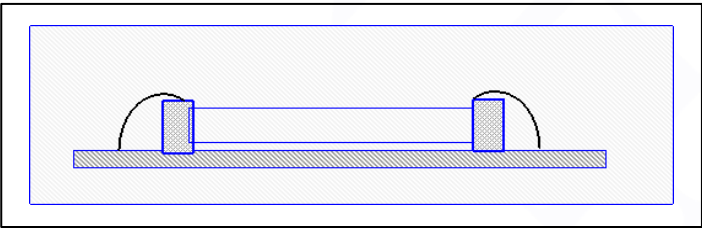
Temperature: 40±2℃ Humidity: 90~95%RH
Duration: 500h
Recovery conditions: Room temperature Recovery Time: 24h (Class1) or 48h (Class2)

Solderability

At least 95% of the terminal electrode is covered by new solder.
Preheating conditions:80 to 120℃; 10~30s.
Solder Temperature:235±5℃ Duration:2±0.5s ,Solder Temperature:245±5℃ Duration:2±0.5s

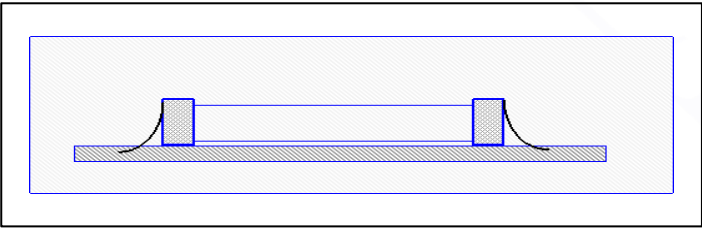
Optimum Solder Amount for Reflow Soldering

Too much solder



Cracks tend to occur due to large stress.

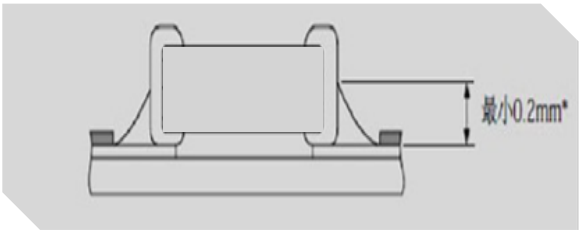
Not enough solder



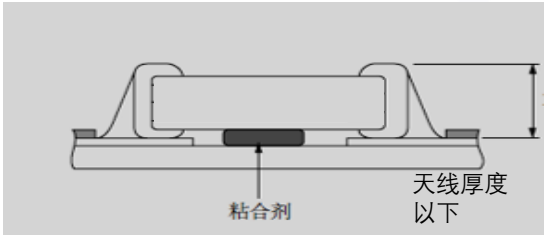
Weak holding force may cause bad connection between the chip and PCB.

Recommended Soldering Amounts

The optimal solder fillet amounts for re-flow soldering



The optimal solder fillet amounts for wave soldering





Temperature Cycle Test

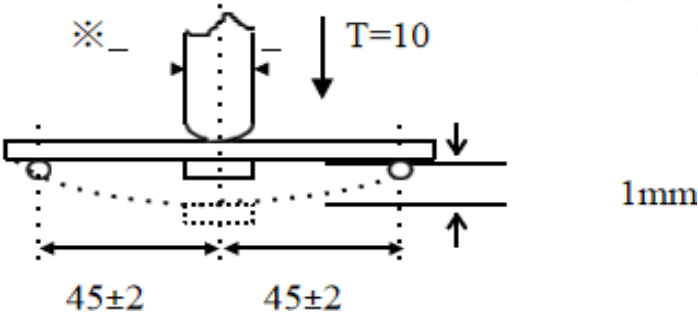
10±1S Applied Force: 5N Duration: 10±1S
Preheating conditions: up-category temperature, 1h
Recovery time: 24±1h
Initial Measurement
Cycling Times: 5 times, 1 cycle, 4 steps:

阶段	温度 (℃)	时间 (分钟)
第 1 步	下限温度(NPO/X7R/X7S/X6S/X5R:-55 Y5V:-25 Z5U:-10)	30
第 2 步	常温 (+20)	2~3
第 3 步	上限温度(NPO/X7R/X7S: +125 Y5V/Z5U/X5R:-85 X6S:-105)	30
第 4 步	常温 (+20)	2~3

Resistance to Soldering Heat

Preheating 80 to 120°C; 10~30s.Solder Temperature: 235±5°C; Duration:2±0.5s; Solder Temperature: 245±5°C
Duration: 2±0.5s; Preheating100 to 200°C; 10±2min.
Solder Temperature: 265±5°C; Duration: 10±1s
Clean the capacitor with solvent and examine it with a 10X(min.) microscope.
Recovery Time: 24±2h
Recovery condition: Room temperature

Resistance to Flexure of Substrate

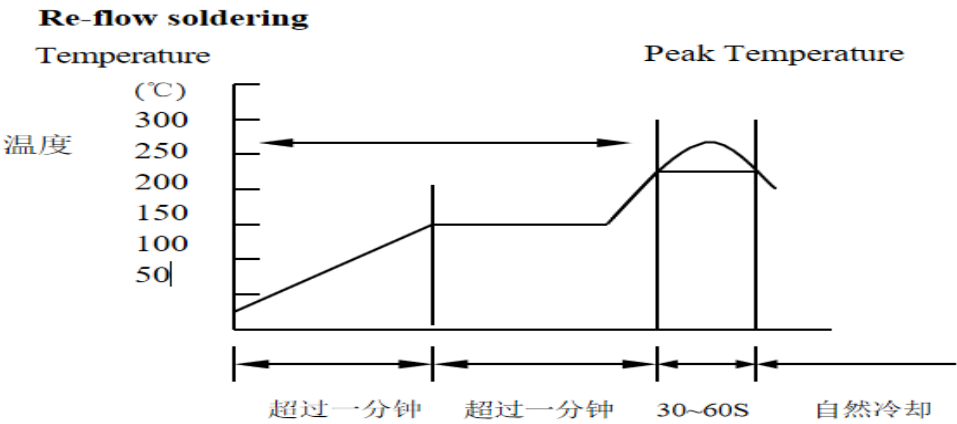


Test Board: Al₂O₃ or PCB Warp: 1mm Speed: 0.5mm/sec.
Unit: mm
The measurement should be made with the board in the bending position.



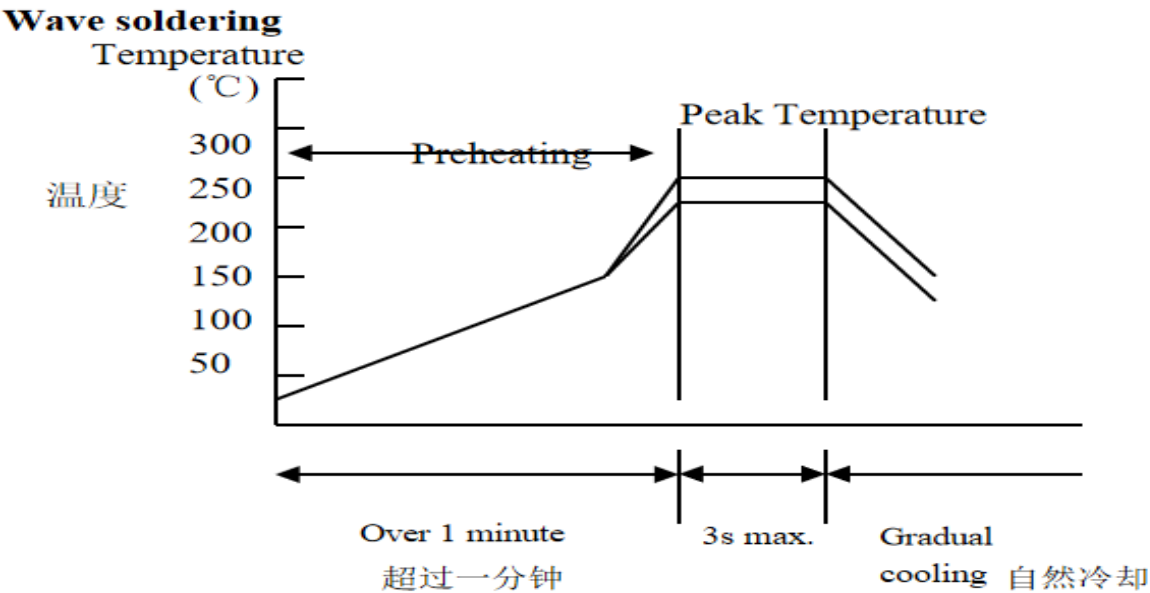
P/N: HY160808 SRF07

The temperature profile for soldering



	Pb-Sn 焊接 Pb-Sn soldering	无铅焊接 Lead-free soldering
尖峰温度 Peak temperature	230℃~250℃	240℃~260℃

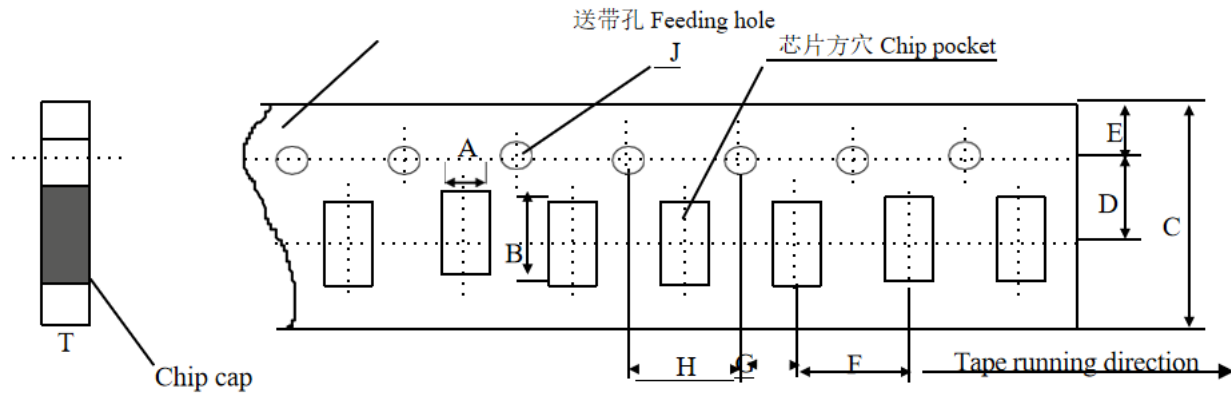
While in preheating, please keep the temperature difference between soldering temperature and surface temperature of chips as: $T \leq 150^{\circ}\text{C}$.



	Pb-Sn 焊接 Pb-Sn soldering	无铅焊接 Lead-free soldering
尖峰温度 Peak temperature	230℃~260℃	240℃~270℃

P/N: HY160808 SRF07

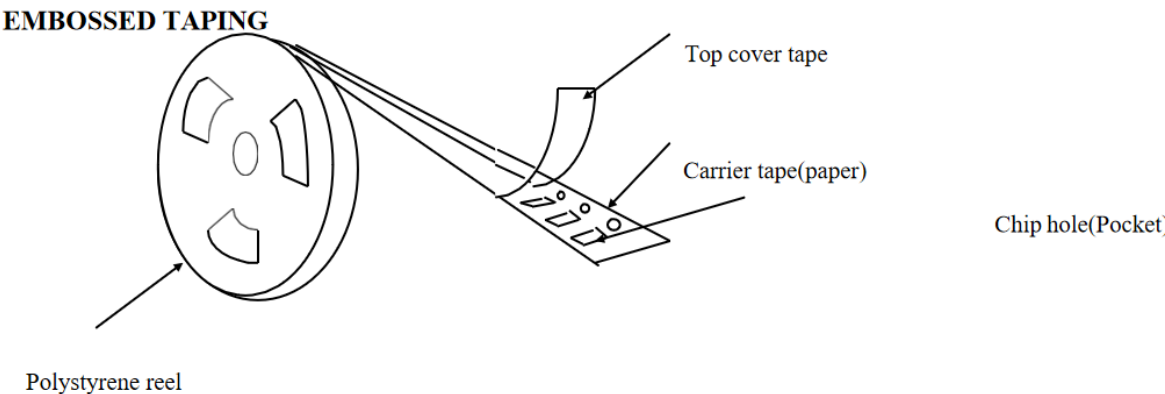
Dimensions of paper taping



Unit: mm

代号Code 纸带规格 papersize	A	B	C	D*	E	F	G*	H	J	T
尺寸	1.10 ±0.10	1.90 ±0.10	8.00 ±0.10	3.50 ±0.05	1.75 ±0.10	4.00 ±0.10	2.00 ±0.10	4.00 ±0.10	1.50 -0/+0.10	1.10 Max

Reel (4000 pcs/Reel)



Storage Period

The guaranteed period for solderability is 6 months (Under deliver package condition).
Temperature:5~40°C /Relative Humidity:20~70%

Hanyang Antenna Design Co. Ltd. has possession of proprietary information provided in this report and this proprietary information shall be kept in strict confidence and not disclosed to any person or firm without the prior written consent of Hanyang Antenna Design Co. Ltd.